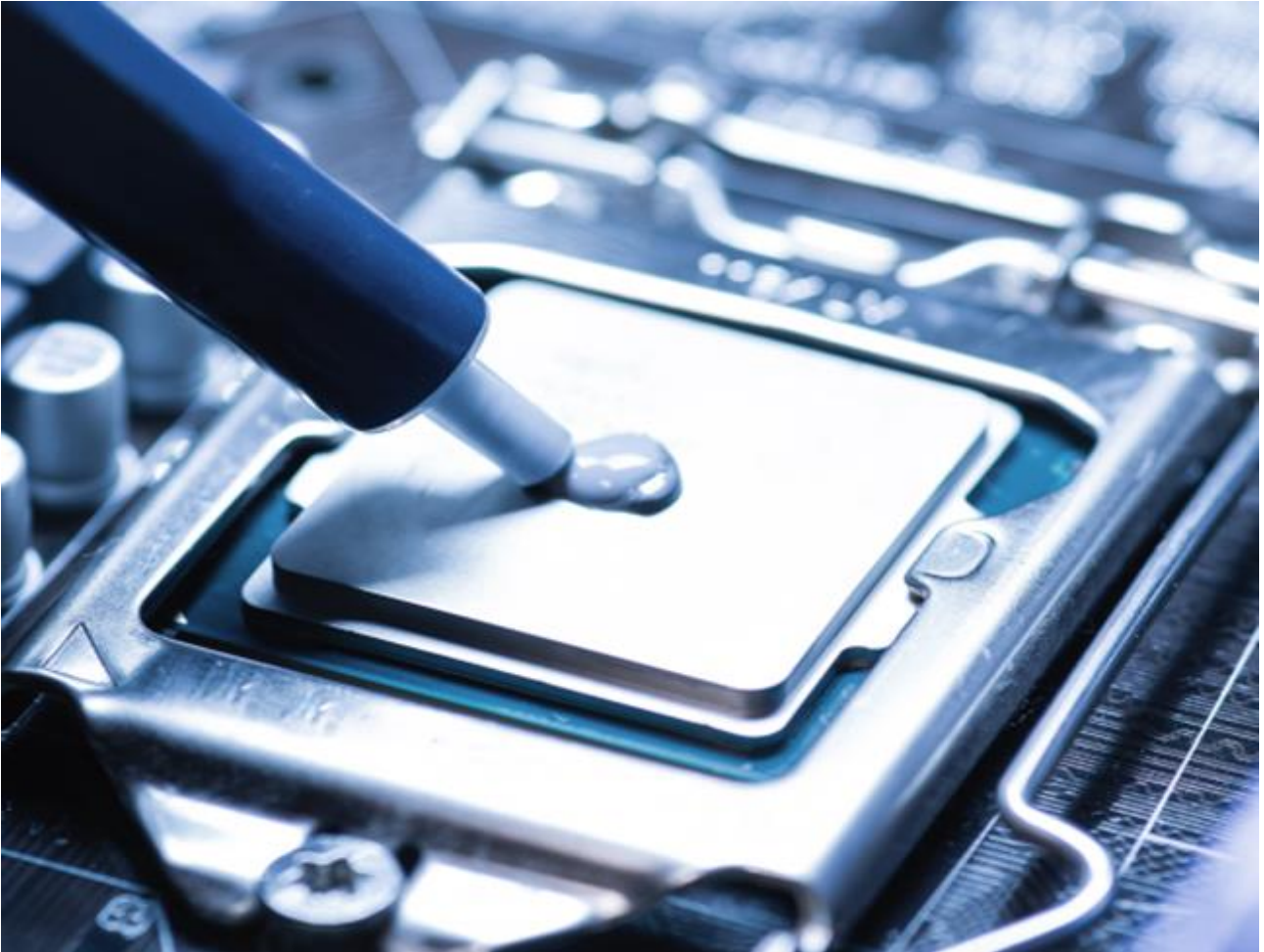


## Aluminas for Thermal Interface Materials

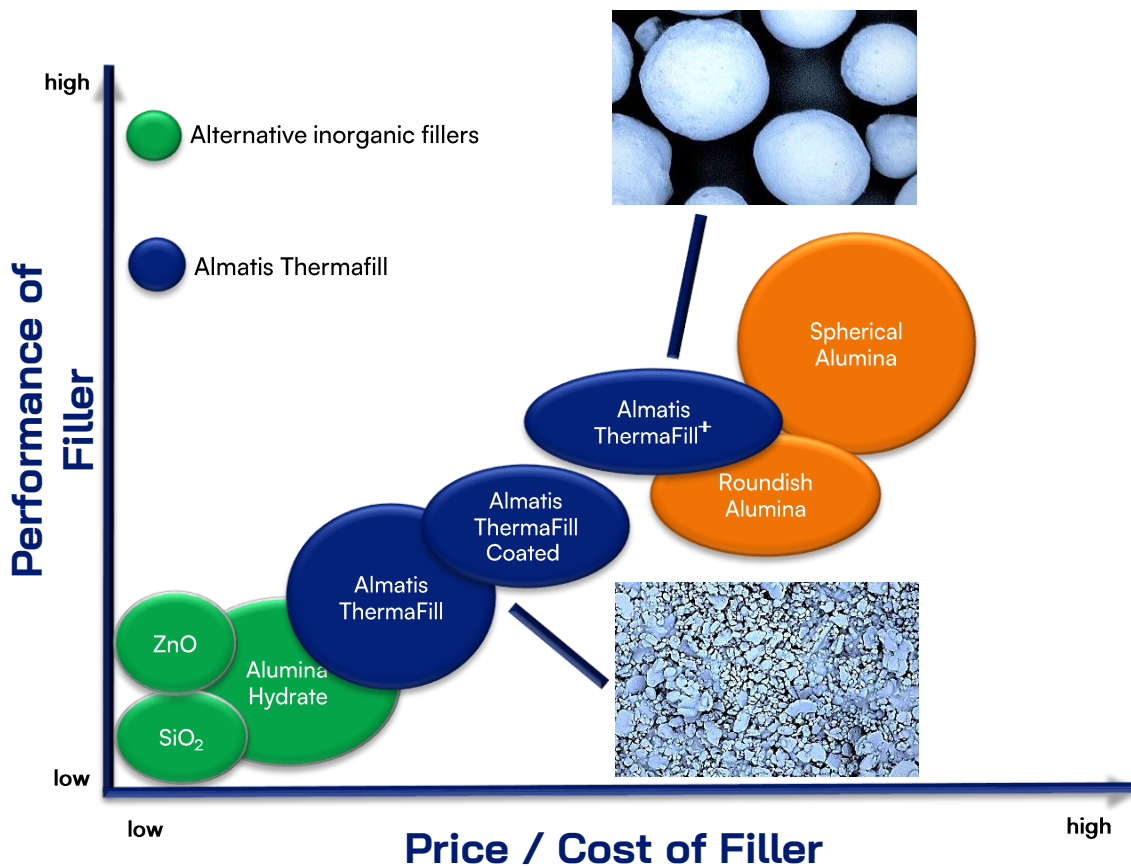




# Aluminas for Thermal Interface Materials

## ThermaFill-Series

ThermaFill products are specially designed alumina fillers to yield higher performance in thermal interface applications. Alumina fillers provide a high value/cost option to increase thermal conductivity in polymer systems such as silicone, epoxy and more. The lower viscosity and higher packing efficiency with ThermaFill products allows a higher filler loading and the potential to increase thermal conductivity further.



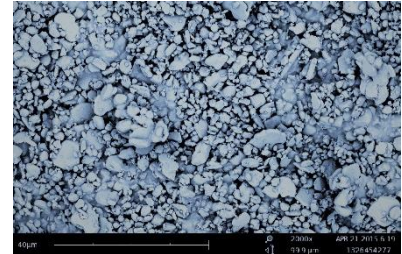


# Aluminas for Thermal Interface Materials

## ThermaFill-Series

ThermaFill products are the economic solution for basic functional filler applications.

The ThermaFill product series is available as a surface treated version, which enables the user to increase the solids loading in compounds for optimized thermal conductivity. There are solutions for Epoxy (E), Silicone (S), Polyol (P) and Urethane (U) available, which are labeled with a suffix accordingly.



SEM Image: ThermaFill 5

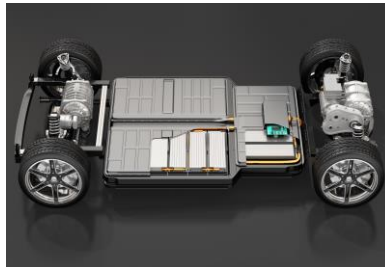
| ThermaFill                             |                     |            |            |            |            |            |            |            |          |            |            |
|--|---------------------|------------|------------|------------|------------|------------|------------|------------|----------|------------|------------|
| Chemical Composition                   | Unit                | 15         | 10         | 9          | 8          | 7          | 5          | 4          | 3        | 2          | 1          |
| Al <sub>2</sub> O <sub>3</sub> Typical | [%]                 | 99.7       | 99.5       | 99.7       | 99.5       | 99.5       | 99.7       | 99.7       | 99.7     | 99.7       | 99.7       |
| Na <sub>2</sub> O Typical              | [%]                 | 0.08       | 0.4        | 0.03       | 0.1        | 0.3        | 0.08       | 0.1        | 0.1      | 0.08       | 0.08       |
| Particle Size Distribution             |                     |            |            |            |            |            |            |            |          |            |            |
|  |                     | Mono-modal | Mono-modal | Mono-modal | Mono-modal | Mono-modal | Mono-modal | Mono-modal | Bi-modal | Mono-modal | Mono-modal |
| D50 Typical*                           | [µm]                | 15         | 10         | 9          | 8          | 7          | 4          | 3          | 3        | 1.2        | 0.5        |
| > 45 µm / 325 mesh                     | [%]                 | ≤10        | ≤5         | ≤5         | ≤5         | ≤1.5       | ≤0.3       | ≤0.1       | ≤0.1     |            |            |
| > 20 µm / 635 mesh                     | [%]                 |            |            |            |            |            | ≤3         |            |          | ≤1         | ≤1         |
| Properties / Method                    |                     |            |            |            |            |            |            |            |          |            |            |
| Specific Surface Area BET Typical      | [m <sup>2</sup> /g] | 0.4        | 0.8        | 0.8        | 0.5        | 1.2        | 0.9        | 2          | 3        | 3          | 7          |

All data are based upon Almatis standard test methods and published as typical or range limits. All test methods are available upon request.

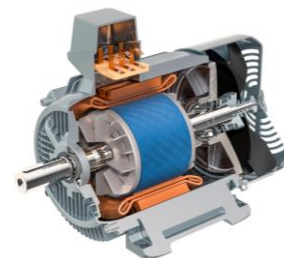
\* Laser granulometry Bettersizer S3 Almatis global standard



APPLICATION: Electronics



APPLICATION: potting materials for battery packs



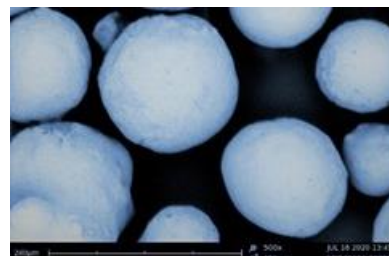
APPLICATION: Encapsulation for electric motors

# Aluminas for Thermal Interface Materials

## ThermaFill<sup>+</sup>

ThermaFill<sup>+</sup> is used as an alumina filler designed to yield a higher performance in polymer resin systems, such as silicone, epoxy, etc., for heat dissipation applications. The higher packing efficiency of ThermaFill<sup>+</sup> compared to standard aluminas allows for a higher filler loading and lower viscosity of the filled resin, offering the potential to significantly increase the thermal conductivity. ThermaFill<sup>+</sup> provides a cost efficient, high value solution for thermal interface materials.

ThermaFill<sup>+</sup> is available as a surface treated version, including Epoxy (E), Silicone (S), Polyol (P) and Urethane (U), which are labeled with a suffix accordingly.



SEM image: ThermaFill<sup>+</sup>

| ThermaFill <sup>+</sup> 80             |                     |            |
|--|---------------------|------------|
| Chemical Composition                   | Unit                | Typical    |
| Al <sub>2</sub> O <sub>3</sub> Content | [%]                 | 99.7       |
| Na <sub>2</sub> O                      | [%]                 | 0.01       |
| Particle Size Distribution             |                     |            |
|  |                     | Mono-modal |
| D50 Typical*                           | [μm]                | 75         |
| > 200 μm / 74 mesh                     | [%]                 | 0.1        |
| < 45 μm / 325 mesh                     | [%]                 | 10         |
| Properties / Method                    |                     |            |
| Specific Surface Area BET Typical      | [m <sup>2</sup> /g] | 0.25       |

The typical properties are based upon the actual averages from production data.

All data are based upon Almatris standard test methods. All test methods are available upon request.

\* Laser granulometry Bettersizer S3 Almatris global standard



APPLICATION: Electronics



APPLICATION: Telecommunication



APPLICATION: EV Mobility

### Standard Packaging

- 25 kg paper bags
- 1000 kg big bags

Contact for sales, technical information and application assistance

**Head Office**  
Almatris GmbH  
Lyoner Straße 9  
60528 Frankfurt/Germany

info@almatris.com  
www.almatris.com

SDS 387